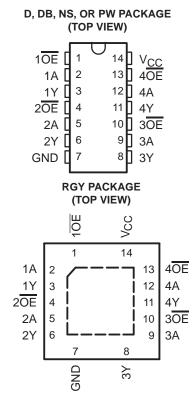
- Operates From 1.65 V to 3.6 V
- Specified From -40°C to 85°C and -40°C to 125°C
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 4.8 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

This quadruple bus buffer gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVC125A features independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (\overline{OE}) input is high.



To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY Reel of 1000		SN74LVC125ARGYR	LC125A
		Tube of 50	SN74LVC125AD	
	SOIC - D	Reel of 2500	SN74LVC125ADR	LVC125A
		Reel of 250	SN74LVC125ADT	
	SOP - NS	Reel of 2000	SN74LVC125ANSR	LVC125A
-40°C to 125°C	SSOP – DB	Reel of 2000	SN74LVC125ADBR	LC125A
		Tube of 90	SN74LVC125APW	
	TSSOP – PW	Reel of 2000	SN74LVC125APWR	LC125A
		Reel of 250	SN74LVC125APWT	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.



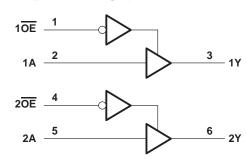
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

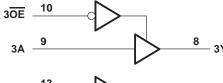


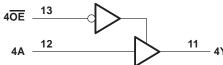
FUNCTION TABLE (each buffer)

INPU	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z

logic diagram (positive logic)







absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 6.5 V
Input voltage range, V _I (see Note 1)	0.5 V to 6.5 V
Output voltage range, VO (see Notes 1 and 2)0.	$.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{ K }(V_1 < 0)$	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through V _{CC} or GND	
Package thermal impedance, θ_{JA} (see Note 3): D package	86°C/W
(see Note 3): DB package	96°C/W
(see Note 3): NS package	76°C/W
(see Note 3): PW package	113°C/W
(see Note 4): RGY package	47°C/W
Storage temperature range, T _{stq}	
Power dissipation, P_{tot} ($T_A = -40^{\circ}$ C to 125°C) (see Notes 5 and 6)	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of V_{CC} is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-5.
 - 5. For the D package: above 70 $^{\circ}\text{C},$ the value of P $_{tot}$ derates linearly with 8 mW/K.
 - 6. For the DB, NS, and PW packages: above 60°C, the value of Ptot derates linearly with 5.5 mW/K.



recommended operating conditions (see Note 7)

			T _A = 25°C		-40 TO 85°C		-40 TO 125°C		
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
.,	V _{CC} Supply voltage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	
vcc	Supply voltage	Data retention only	1.5		1.5		1.5		V
		V _{CC} = 1.65 V to 1.95 V	0.65×V _{CC}		0.65×V _{CC}		0.65×V _{CC}		
۷ıн	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		1.7		1.7		V
	voltage	V _{CC} = 2.7 V to 3.6 V	2		2		2		
		V _{CC} = 1.65 V to 1.95 V		0.35×V _{CC}		0.35×V _{CC}		0.35×V _{CC}	
۷ _{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V		0.7		0.7		0.7	V
	voltago	V _{CC} = 2.7 V to 3.6 V		0.8		0.8		0.8	
٧ _I	Input voltage		0	5.5	0	5.5	0	5.5	٧
VO	Output voltage		0	VCC	0	VCC	0	Vcc	V
		V _{CC} = 1.65 V		-4		-4		-4	
	High-level output	V _{CC} = 2.3 V		-8		-8		-8	A
ІОН	current	V _{CC} = 2.7 V		-12		-12		-12	mA
		V _{CC} = 3 V		-24		-24		-24	
		V _{CC} = 1.65 V		4		4		4	
1	Low-level output	V _{CC} = 2.3 V		8		8		8	mA
lOL	current	V _{CC} = 2.7 V		12		12		12	
		V _{CC} = 3 V		24		24		24	mA
Δt/Δν	Input transition rise	or fall rate		8		8		8	ns/V

NOTE 7: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN74LVC125A QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

SCAS290N - JANUARY 1993 - REVISED FEBRUARY 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		.,	T _A = 25°C			-40 TO 8	35°C	–40 TO 125°C			
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
Voн	I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} -0.2			V _{CC} -0.2		V _{CC} -0.3			
	I _{OH} = -4 mA	1.65 V	1.29			1.2		1.05			
	I _{OH} = -8 mA	2.3 V	1.9			1.7		1.55		.,	
		2.7 V	2.2			2.2		2.05		V	
	I _{OH} = -12 mA	3 V	2.4			2.4		2.25			
	I _{OH} = -24 mA	3 V	2.3			2.2		2			
	I _{OL} = 100 μA	1.65 V to 3.6 V			0.1		0.2		0.3	V	
	I _{OL} = 4 mA	1.65 V			0.24		0.45		0.6		
VOL	I _{OL} = 8 mA	2.3 V			0.3		0.7		0.75		
	I _{OL} = 12 mA	2.7 V			0.4		0.4		0.6		
	I _{OL} = 24 mA	3 V			0.55		0.55		8.0		
lį	V _I = 5.5 V or GND	3.6 V			±1		±5		±20	μΑ	
loz	$V_O = V_{CC}$ or GND	3.6 V			±1		±10		±20	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			1		10		40	μΑ	
ΔlCC	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V			500		500		5000	μА	
Ci	V _I = V _{CC} or GND	3.3 V		5						pF	

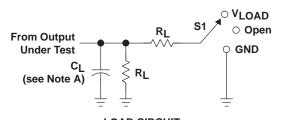
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	.,	T,	ղ = 25°C	;	-40 TO	85°C	-40 TO	125°C	
PARAMETER	(INPUT)	(OUTPUT)	v _{CC}	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			1.8 V ± 0.15 V	1	4.5	11.8	1	12.3	1	13.8	
		V	2.5 V ± 0.2 V	1	2.7	5.8	1	6.3	1	8.4	
^t pd	Α	Υ	2.7 V	1	3	5.3	1	5.5	1	7	ns
			3.3 V ± 0.3 V	1	2.5	4.6	1	4.8	1	6	
	ŌĒ	Y	1.8 V ± 0.15 V	1	4.3	13.8	1	14.3	1	15.8	ns
			2.5 V ± 0.2 V	1	2.7	6.9	1	7.4	1	9.5	
t _{en}			2.7 V	1	3.3	6.4	1	6.6	1	8.5	
			$3.3~\text{V}\pm0.3~\text{V}$	1	2.4	5.2	1	5.4	1	7	
	ŌĒ		1.8 V ± 0.15 V	1	4.3	10.6	1	11.1	1	12.6	ns
^t dis		Y	2.5 V ± 0.2 V	1	2.2	5.1	1	5.6	1	7.7	
			2.7 V	1	2.5	4.8	1	5	1	6.5	
			$3.3~\text{V}\pm0.3~\text{V}$	1	2.4	4.4	1	4.6	1	6	
t _{sk(o)}			3.3 V ± 0.3 V					1		1.5	ns

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	VCC	TYP	UNIT
			1.8 V	7.4	pF
C _{pd}	Power dissipation capacitance per gate	f = 10 MHz	2.5 V	11.3	
			3.3 V	15	

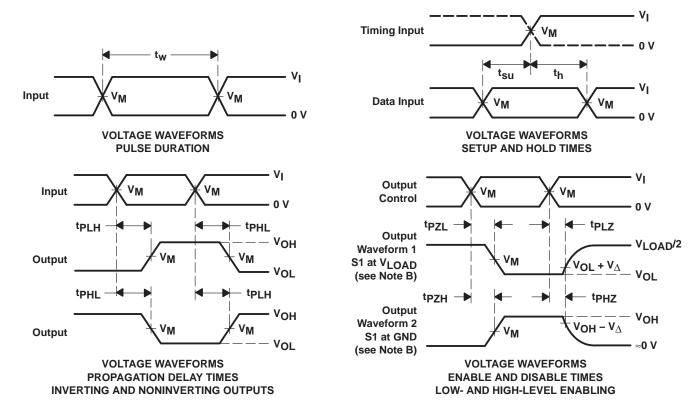
PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

LUAD	CIRCUIT

.,	INPUTS		.,	.,	_	_	.,
VCC	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
1.8 V \pm 0.15 V	VCC	≤2 ns	V _{CC} /2	2×VCC	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤ 2 ns	V _{CC} /2	2×VCC	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V

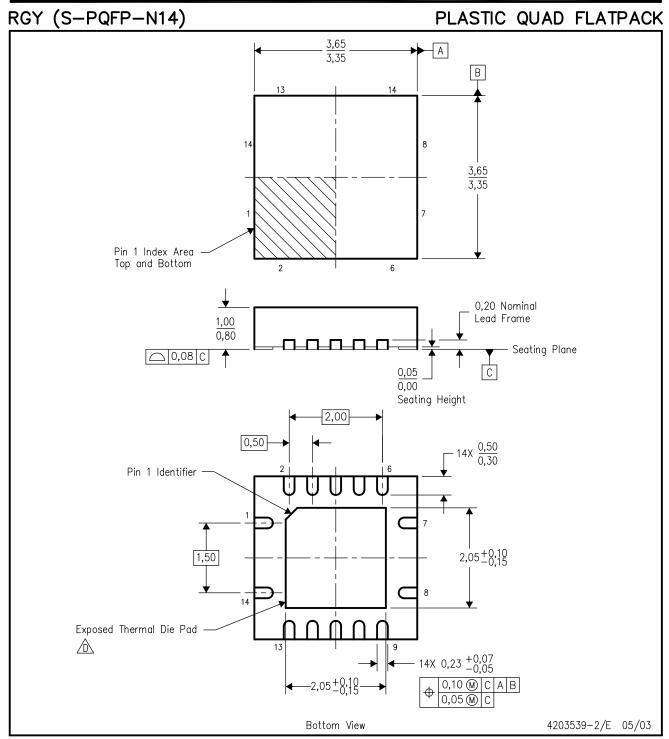


NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzI and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





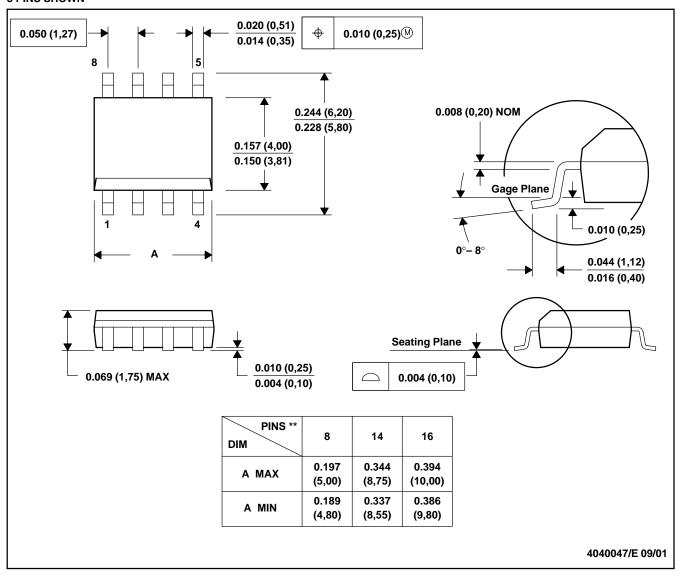
- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
 - E. Package complies to JEDEC MO-241 variation BA.



D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

e
d
trol
work
d trol wo

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2004, Texas Instruments Incorporated